



Minor Modification in the Package Outline Specification of Thermally Enhanced BG and FG Series Packages Meeting the JEDEC-MO-191

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Product Change Notice

Overview

Minor modification in the package outline specification of thermally enhanced BG and FG series packages meeting the JEDEC-MO-191.

Affected Package codes:

- BG352 - Xilinx reference [PK019](#)
- BG432 - Xilinx reference [PK020](#)
- BG560 - Xilinx reference [PK021](#)
- FG680 - Xilinx reference [PK036](#)

Description

Xilinx is modifying the specification that controls the mechanical dimensions of the copper heatsink on these BGA packages. The current specification implied a heatsink that is coincident with the package body. The proposed modification will allow the heatsink to be pulled back from the edge by a maximum of 0.375 mm (14.7 mils) per side. The current products will meet the change since their heatsink is coincident (0.0 pull back) with the package.

The attached outline drawings show the change in the actual package outlines. No other change is made in the package outline specification. There is no functional change in product performance or characteristics.

Reason for Change

This minor physical change in heatsink specification will allow Xilinx to consider piece-parts from other sources. The new specification will allow alternate sources to meet the outline drawing, and more importantly to support the anticipated growing needs of the enhanced BGA packages.

Key Dates

The specification change is immediate. Products with coincident heatsinks will continue to ship and these will continue to meet the specification. Qualification testing of product with pull back heatsinks will be completed prior to shipment of product. This data will be available upon request via email at pcn@xilinx.com.

Xilinx plans to ship product with pull back heatsinks meeting the new specification during January, 2001.

Traceability

Products built with non-coincident heatsink can be recognized by sight. We consider the physical change to be minor with no functional changes in product performance or characteristics.

Response

No response is required by this notice. For additional information or questions, please contact [Xilinx Technical Support](#).

Important Notice: Xilinx Customer Notifications (XCNs, XDNs, and Quality Alerts) can be delivered via e-mail alerts sent by the MySupport website (<http://www.xilinx.com/support>). Register today and personalize your "MyAlerts" area to include Customer Notifications. This change provides many benefits, including the ability to receive alerts for new and updated information about specific products, as well as alerts for other publications such as data sheets, errata, application notes, etc. For information on how to sign up, refer to [Xilinx Answer Record 18683](#).

Revision History

The following table shows the revision history for this document.

Date	Version	Revision
10/5/00	1.0	Initial Xilinx release.
3/13/07	1.0.1	Updated the Overview section; corrected links to Package Drawings.